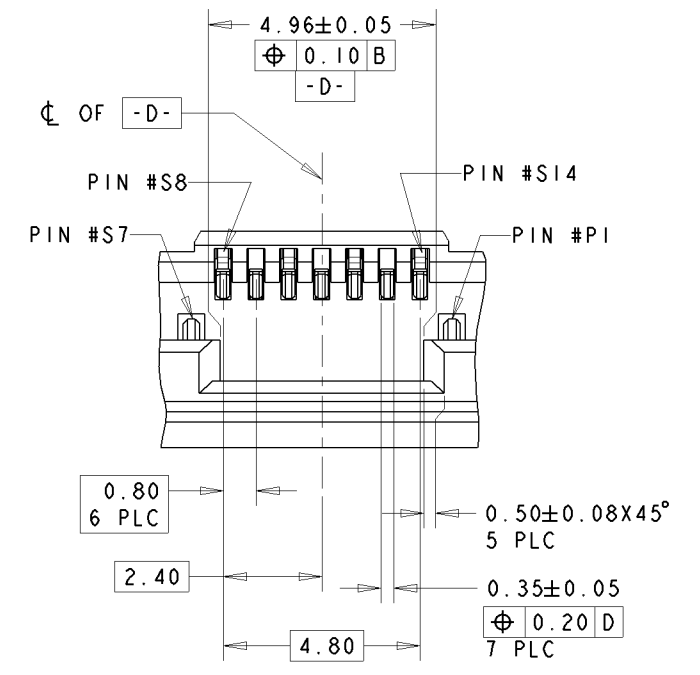
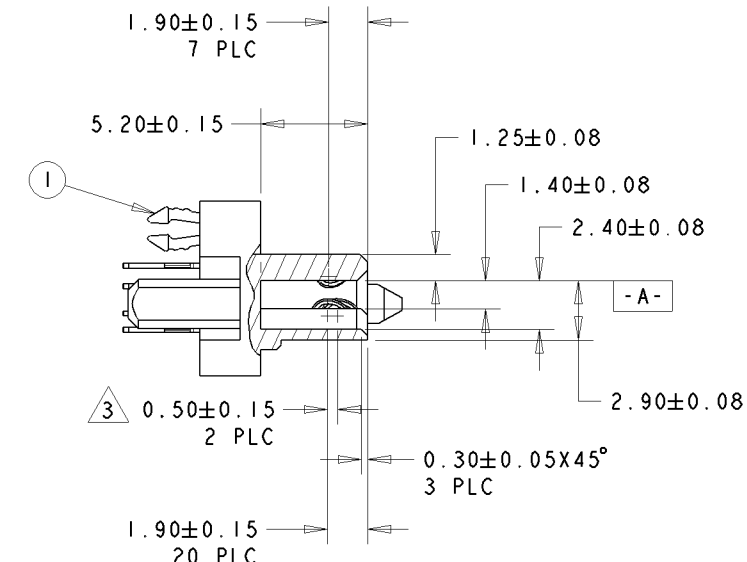
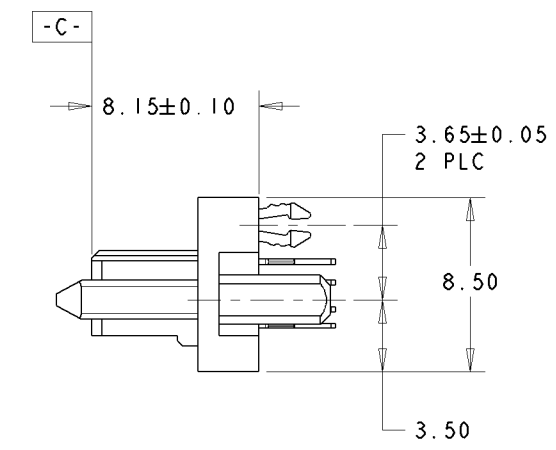
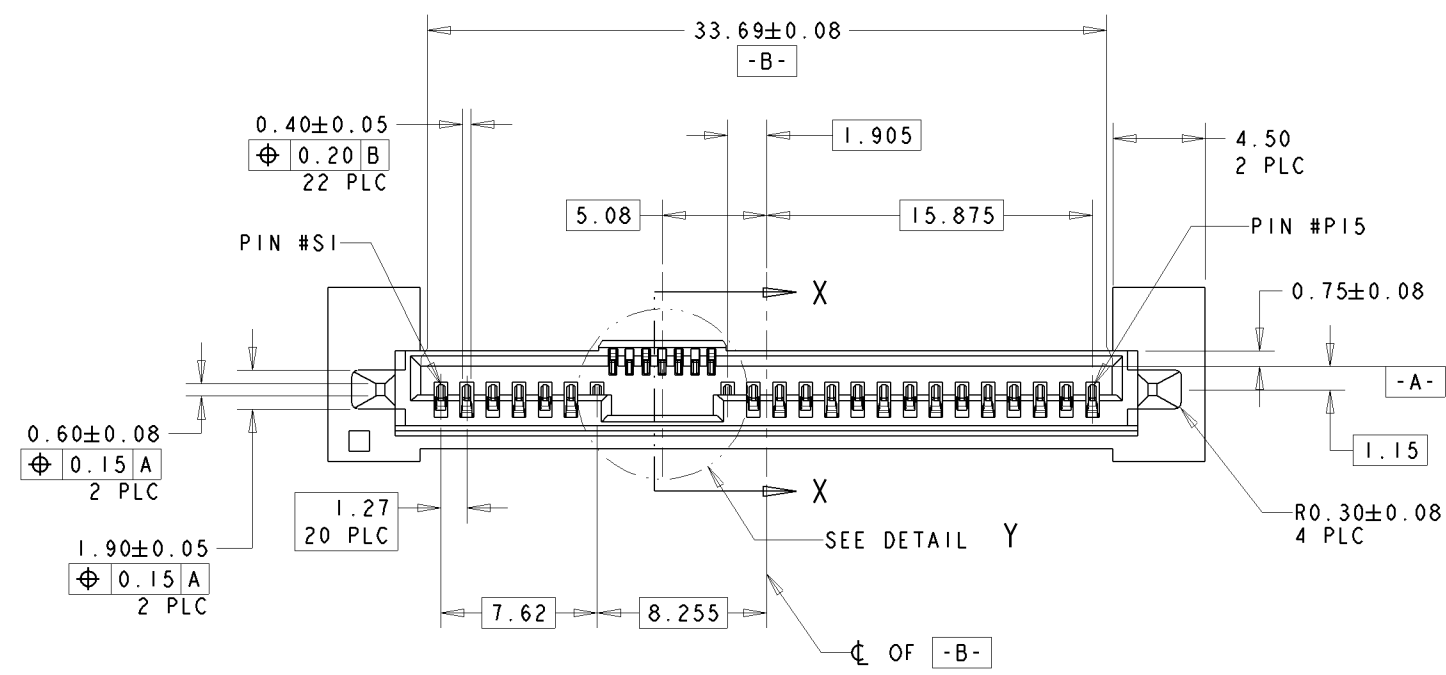


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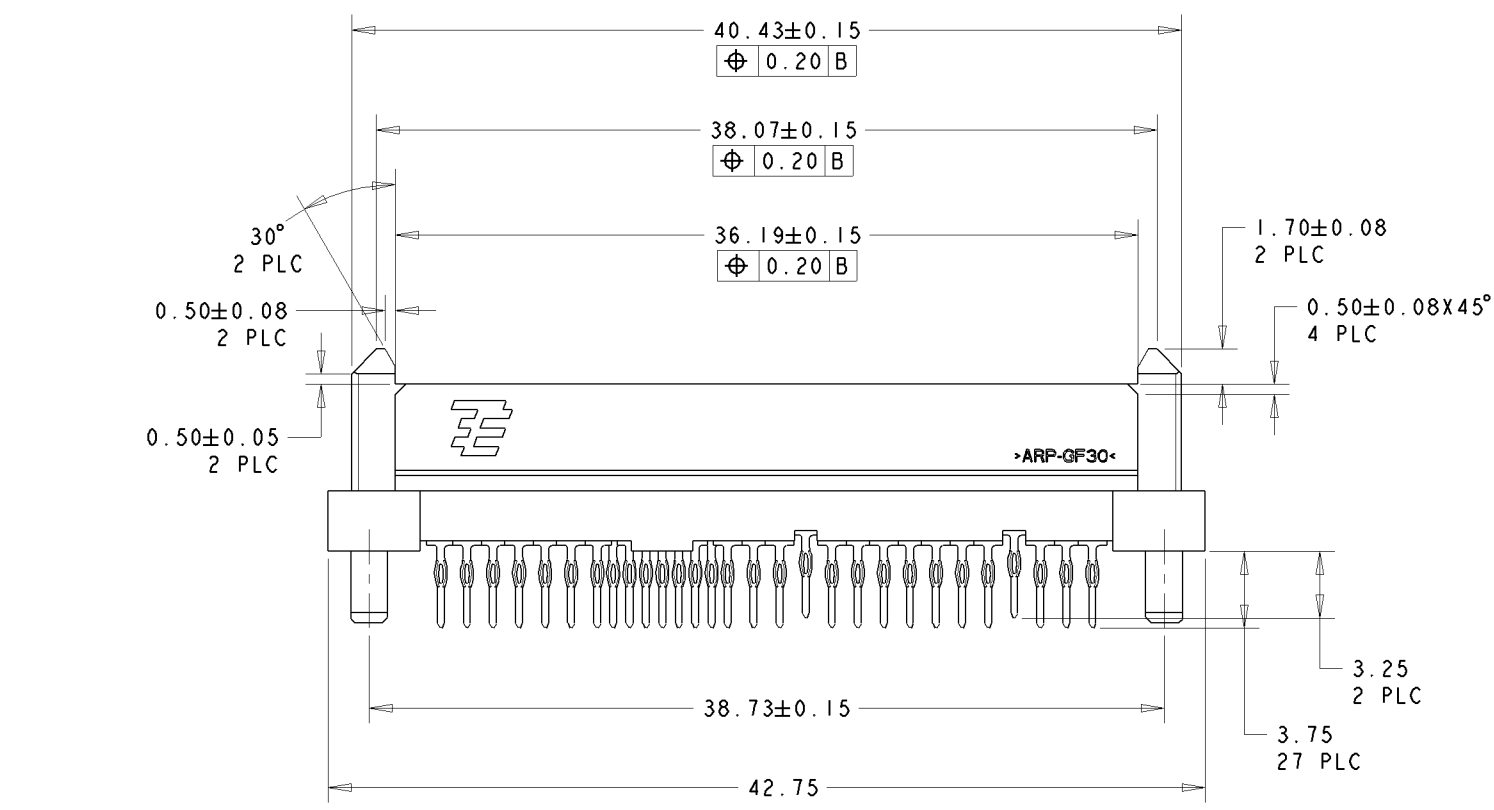
LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
DY	-	B	REVISED ECR-10-012418	11JUN10	LSK LSF

NOTES:

- 1 MATERIAL:
HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0,
COLOR: BLACK
CONTACT: COPPER ALLOY
BOARDLOCK: COPPER ALLOY
- 2 FINISH:
CONTACT AREA: MIN 0.76um GOLD PLATING
SOLDERTAIL: MIN 2.54um MATTE TIN PLATING
UNDERPLATE: MIN 1.27um NICKEL PLATING
- 3 PIN #P4 AND #P12 ONLY



DETAIL Y
SCALE 8:1



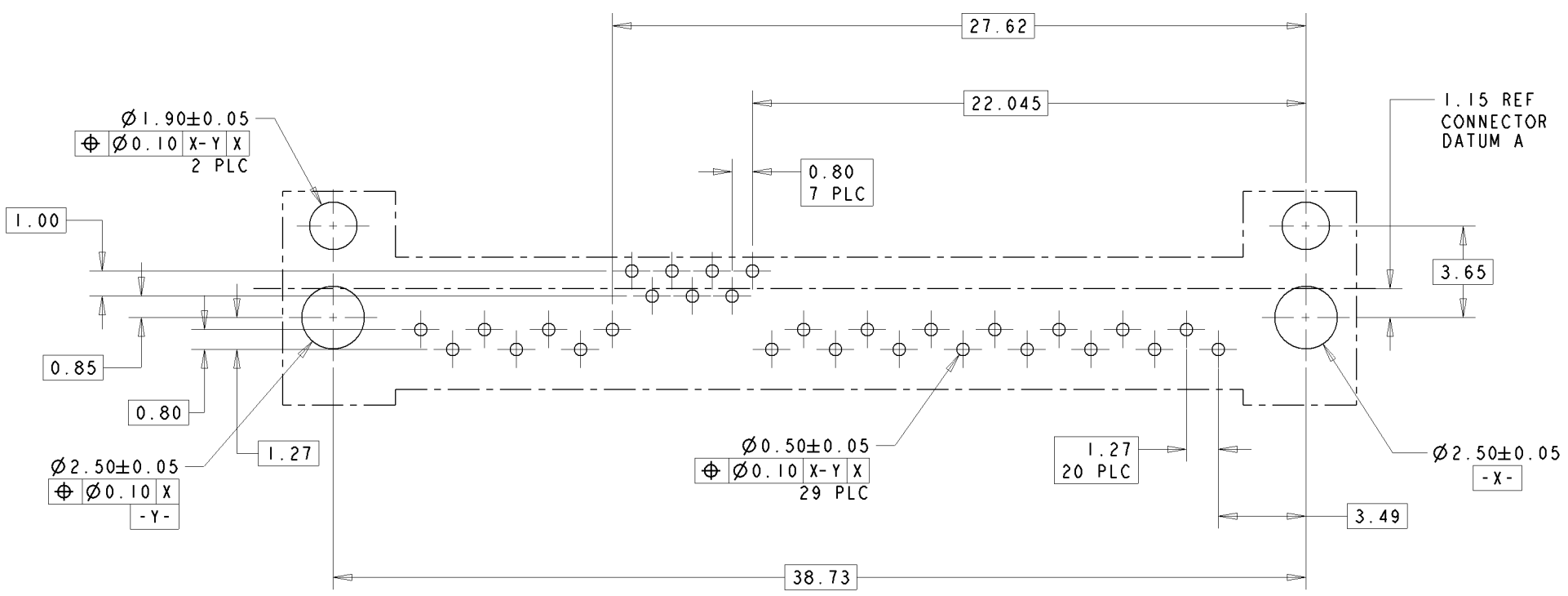
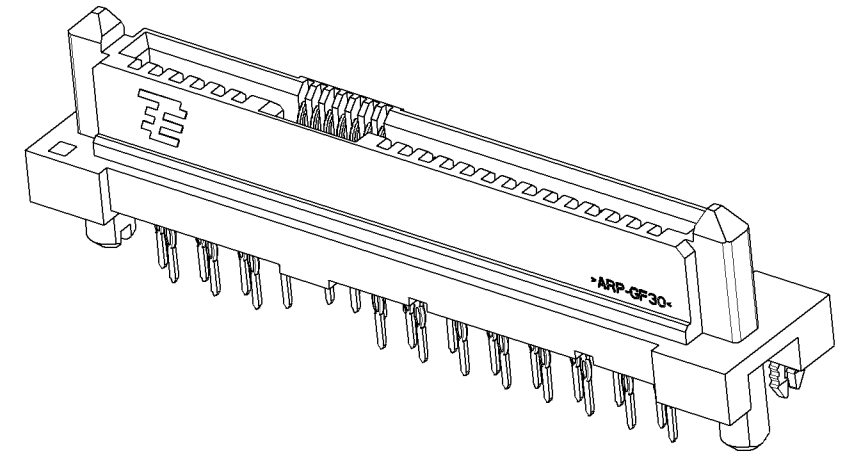
DIMENSIONS - mm		TOLERANCES UNLESS OTHERWISE SPECIFIED:	
0 PLC	±	0.20	±
1 PLC	±	0.25	±
2 PLC	±	0.30	±
3 PLC	±	0.40	±
4 PLC	±	0.50	±
ANGLES	±	3°	±
FINISH	2		

DWN	SK LEAW	10JUN2005	Tyco Electronics Singapore Pte. Ltd.	
CHK	SF LEONG	10JUN2005	NAME	
APVD	SF LEONG	10JUN2005	SAS BACKPLANE RECEPTACLE, VERTICAL, PRESS-FIT	
PRODUCT SPEC	108-51067	APPLICATION SPEC	SIZE	A2
114-51013	WEIGHT	-	CAGE CODE	00779
CUSTOMER DRAWING	DRAWING NO		C=1735164	SCALE
	4:1		SHEET	1 of 2
			REV	B

NO	1735164-2
YES	1735164-1
BOARDLOCK (1)	PART NUMBER

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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
DY	-	SEE SHEET 1	-	-	-



RECOMMENDED PCB LAYOUT
 SCALE 6:1

<small>THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.</small>		DWN SK LEAW 10JUN2005 CHK SF LEONG 10JUN2005 APVD SF LEONG 10JUN2005	Tyco Electronics Singapore Pte. Ltd.
DIMENSIONS - mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.20 3 PLC ± 4 PLC ± ANGLES ±3° FINISH -	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, PRESS-FIT PRODUCT SPEC 108-51067 APPLICATION SPEC 114-51013 WEIGHT -	SIZE A2 CAGE CODE 00779 DRAWING NO C=1735164
MATERIAL -		CUSTOMER DRAWING	
		SCALE 4:1	SHEET 2 OF 2 REV B